PATENT ABSTRACTS OF JAPAN

(11) Publication number:

62-021250

(43) Date of publication of application: 29.01, 1987

(51) int. CI.

H01L 23/28 H01L 21/58

(21) Application number : 60-160257

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(22) Date of filing:

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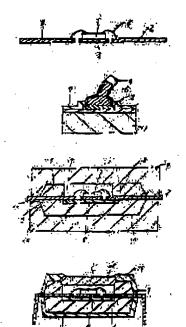
(54) RESIN-SEALED SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

(57) Abstract:

PURPOSE: To manufacture a device wherein the EP-ROM package is plasticized, by forming a resin-molded form which is opened above the chip to include a lead frame, and constructing a resin-sealed type package wherein a transparent glass cover portion is bonded to the opening portion.

CONSTITUTION: A divided Si semiconductor chip 1 is connected to the tab 3 of a lead frame, which consists of a lead 2 and the tab 3. then, bonding is performed between the Al

I ctrode exposed on the chip surface and each lead 2 with an Al wire 4. Next, an insulating protective film 6 of alumina is formed on the surface of the wire 4. And a plate 8 is bonded to the under surface of the frame 2, 3. Further, the lead frame is loaded into molds 9, 10, and resin 11 is molded to form a primary resin-molded form 13. A transparent glass plate 14 is inserted in the opening of the molded form 13 taken out from the molds, and adhesive sealing is performed. The molded form 13 is again placed in the molds, and a secondary resin-molded form 19 is formed by resin molding. And the lead is separated at the projected portion of the lead frame of the molded form 19 taken out.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date_of_requesting_appeal_against_examiner's ___ decision of rejection]

[Date of extinction of right]